

Product Summary (@T_A = +25°C)

V _{RRM} (V)	I _O (A)	V _F (V)	I _R (μA)
1,000	3	1.8	10

Description

3.0A Surface Mount Glass Passivated Rectifier in SMC package offers high current capability and ultra-fast recovery time for high efficiency. Designed with glass passivated die construction for high reliability, this device is ideal for applications such as:

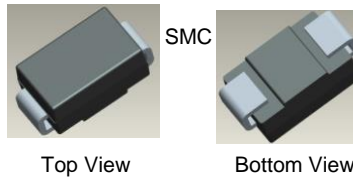
- Power Supplies
- Lighting Ballasts

Features and Benefits

- Glass Passivated Die Construction
- High Current Capability
- Ultra-Fast Recovery Time for High Efficiency
- Maximum Operating Junction Temperature of +175°C
- **Lead Free Finish; RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. “Green” Device (Note 3)**

Mechanical Data

- Case: SMC
- Case Material: Molded Plastic.
UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020D
- Terminals: Lead-Free Plating (Matte Tin Finish).
Solderable per MIL-STD-202, Method 208 (E3)
- Polarity: Cathode Band or Cathode Notch
- Weight: 0.21 grams (Approximate)



Top View

Bottom View

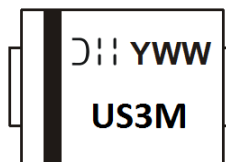
Ordering Information (Note 4)

Part Number	Case	Packaging
US3M-13	SMC	3,000/Tape & Reel

- Notes:
1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. All applicable RoHS exemptions applied.
 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 4. For packaging details, go to our website at <http://www.diodes.com/products/packages.html>.

Marking Information

SMC



US3M = Product Type Marking Code
 D|| = Manufacturer's Code Marking
 YWW = Date Code Marking
 Y = Last Digit of Year (ex: 4 for 2014)
 WW = Week Code 01 to 53

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load.
For capacitance load, derate current by 20%.

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage	V _{RRM}	1,000	V
Working Peak Reverse Voltage	V _{RWM}		
DC Blocking Voltage	V _R		
RMS Reverse Voltage	V _{R(RMS)}	700	V
Average Rectified Output Current @ T _T = +75°C	I _O	3.0	A
Non-Repetitive Peak Forward Surge Current, 8.3ms Single Half Sine-Wave Superimposed on Rated Load	I _{FSM}	120	A

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Typical Thermal Resistance, Junction to Terminal (Note 7)	R _{θJT}	26	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-65 to +175	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 5)	V _{(BR)R}	1,000	—	—	V	I _R = 10μA
Forward Voltage	V _F	—	1.5	1.8	V	I _F = 3.0A
Leakage Current (Note 5)	I _R	—	2.2	10	μA	V _R = 1,000V, T _A = +25°C V _R = 1,000V, T _A = +125°C
Reverse Recovery Time	t _{rr}	—	70	85	ns	I _F = 0.5A, I _R = 1.0A, I _{rr} = 0.25A
Total Capacitance	C _T	—	25	—	pF	V _R = 4V, f = 1.0MHz

- Notes:
5. Short duration pulse test used to minimize self-heating effect.
 6. Device mounted on FR-4 substrate, 1" x 1", 2oz, single-sided, PC boards with 0.15" x 0.26" copper pads.
 7. Device mounted on FR-4 substrate, 1" x 1", 2oz, single-sided, PC boards with 0.56" x 0.73" copper pads.

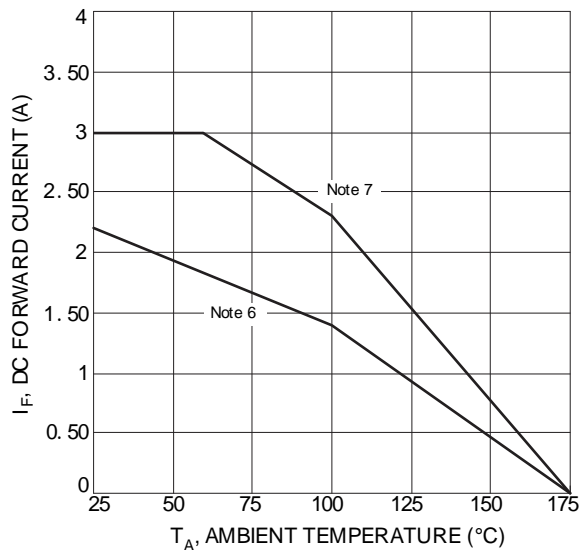


Figure 1 DC Forward Current Derating

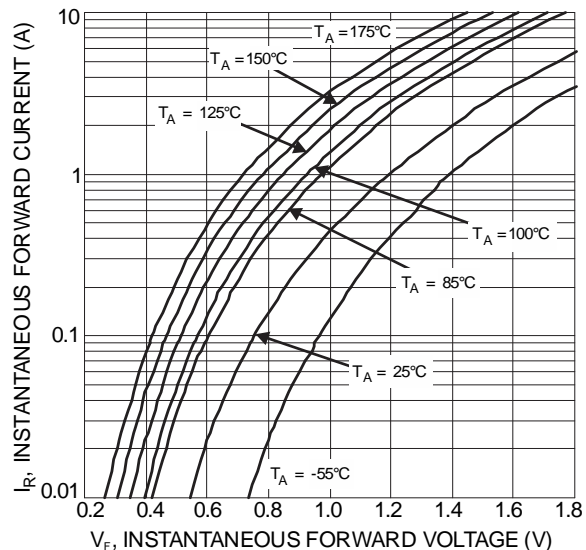


Figure 2 Typical Reverse Characteristics

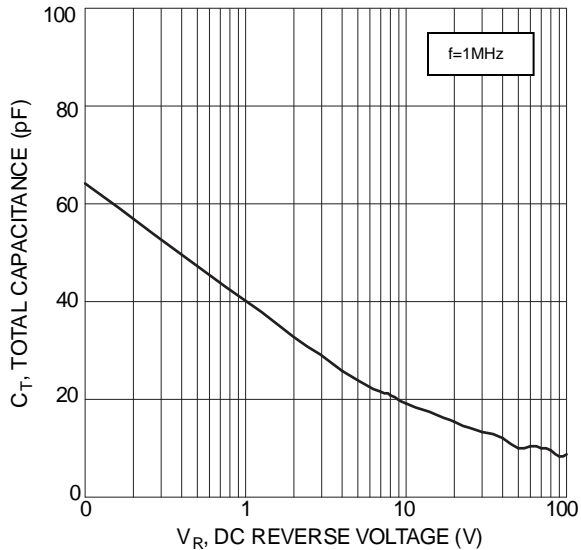


Figure 3 Total Capacitance vs. Reverse Voltage

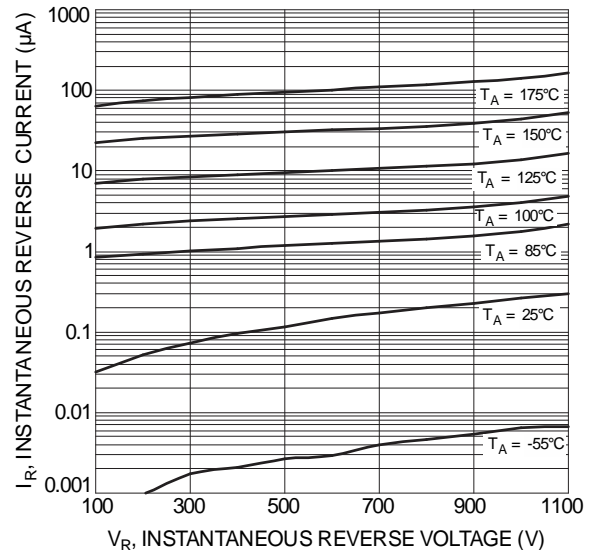
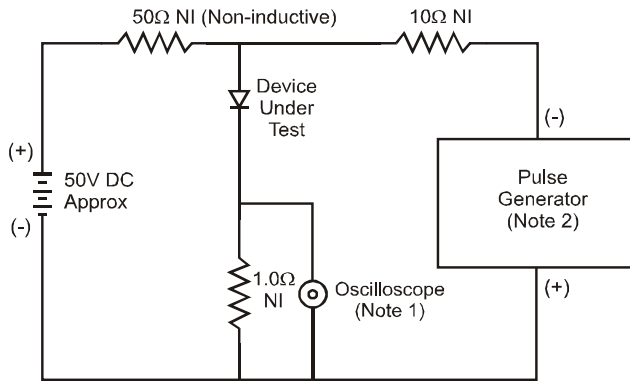
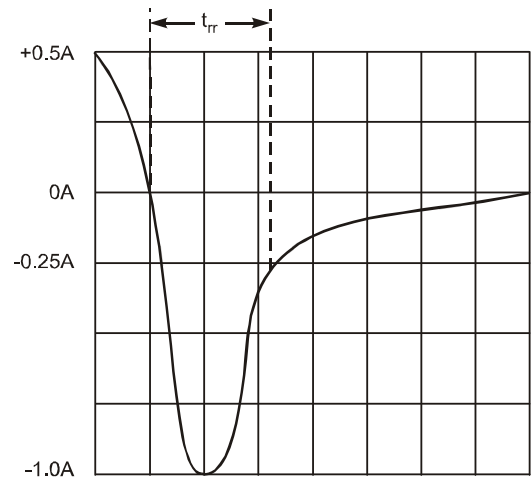


Figure 4 Typical Reverse Characteristics



- Notes:
1. Rise Time = 7.0ns max. Input Impedance = 1.0MΩ, 22pF.
 2. Rise Time = 10ns max. Input Impedance = 50Ω.

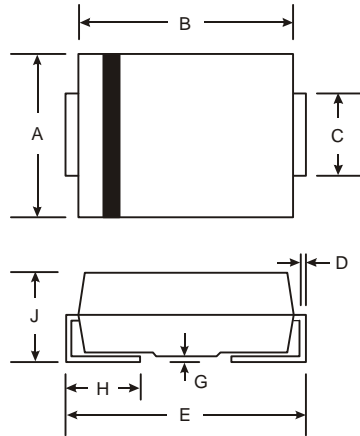


Set time base for 50/100 ns/cm

Figure 5 Reverse Recovery Time Characteristic and Test Circuit

Package Outline Dimensions

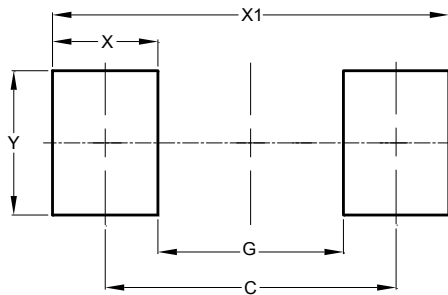
Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for the latest version.



SMC		
Dim	Min	Max
A	5.59	6.22
B	6.60	7.11
C	2.75	3.18
D	0.15	0.31
E	7.75	8.13
G	0.10	0.20
H	0.76	1.52
J	2.00	2.50
All Dimensions in mm		

Suggested Pad Layout

Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.



Dimensions	Value (in mm)
C	6.90
G	4.40
X	2.50
X1	9.40
Y	3.30

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